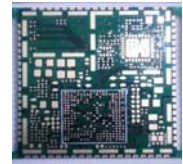


# Printed Circuit Board **Customized**



## FEATURES

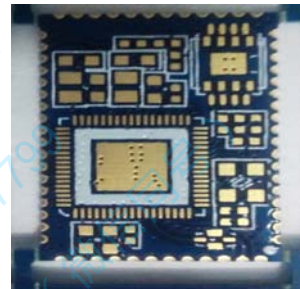
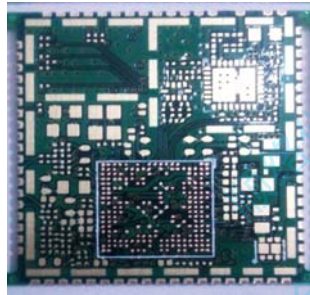
- Advanced manufacture equipments and reliability testing devices, ensuring excellent PCB quality and reliability;
- High THP consistency, high characteristic impedance consistency due to introducing tight tolerance impedance measuring devices;
- High drilling accuracy and good drilling hole shape, Max. AR 8:1 is capable.

## APPLICATIONS

- Wi-Fi, Bluetooth, 3G/4G communication module etc. stamp hole board;
- Consumer electronics, such as LCD-TV, STB, etc.;
- Communication terminals, such as mobile phone, MID, etc;
- Industrial electronic instrument, automotive, etc.

## PRODUCTS PRESENTATION

Stamp Hole Module Board



General HDI Board



HDI 1+4+1



HDI 1+6+1

General HDI Board



HDI 1+1+4+1+1



HDI 1+1+6+1+1

# Sunlord

Specifications subject to change without notice. Please check our website for latest information. Revised 2017/04/15

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## PRODUCTS PRESENTATION

### General Through-Hole Board



4 Layers



6 Layers



8 Layers



10 Layers

## PROCESS CAPABILITY

Through-hole Multilayer Board Capability	4-16 Layers, Board Thickness: 12mil-90mil (0.30mm-2.4mm)
Blind/Buried Hole Capability	4-16 Layers, Board Thickness: 12mil-90mil (0.30mm-2.4mm)
HDI Capability	3+N+3
Primary Material Supplier	Shengyi & EMC & ITEQ
Environmental Production	ROHS, Halogen-Free Compliant Through-hole Multilayer Board and HDI Board
Surface Finish	OSP: Entek Plus Ht, Preflux F2 Lx(0.2-0.5 $\mu$ m)
	Ni:100~250 $\mu$ m(2.54-6.25 $\mu$ m) Au/Ni Immersion: 1~ 5 $\mu$ m(0.03-0.125 $\mu$ m);
	OSP: Entek Plus Ht, Preflux F2 Lx(0.2-0.5 $\mu$ m) Ni:100~250 $\mu$ m(2.54-6.25 $\mu$ m) Au/Ni Immersion: 1~ 5 $\mu$ m(0.03-0.125 $\mu$ m);
Max Production Board Size	21.5" $\times$ 24.5"(546mm $\times$ 622mm)
Max Aspect Ratio	8:1

## PROCESS CAPABILITY

Items	Current Status	Improved Accuracy
Min. Stamp Hole Aperture	12mil(0.3mm)	10mil(0.25mm)
Min.VIA Hole Size	8mil (0.200mm)	5mil (0.150mm)
Min. Blind Hole Size	4mil (0.1mm)	3mil (0.076mm)
Line Width/Space	2.5mil (0.063mm)	2mil (0.05mm)
Line Width/Space Accuracy	+/-20%	+/-10%
PTH Aperture Size Accuracy	+/-3mil (0.075mm)	+/-2mil (0.050mm)
NPTH Aperture Size Accuracy	+/-2mil (0.050mm)	+/-1mil (0.025mm)
Hole Location Accuracy	+/-3mil (0.075mm)	+/-2mil (0.050mm)
Hole to side Accuracy	+/-4mil (0.100mm)	+/-3mil (0.075mm)
Side to Side Accuracy	+/-4mil (0.1mm)	+/-3mil (0.075mm)
Layer to Layer Registration Accuracy	+/-4mil (0.100mm)	+/-3mil (0.075mm)
Impedance Accuracy	+/-10%	+/-7%
Board Twist	Max. 0.75%	Max. 0.5%

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